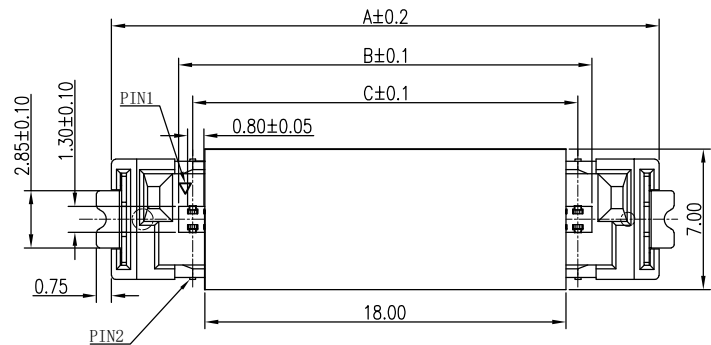


NOTES:

MATERIAL:

- 1.HOUSING:THERMO-PLASTIC. UL 94V-0 NATURE
- 2.CONTACT:PHOSPHOR BRONZE
CONTACT:SEE ORDER INFORMATION; SOLDER:GOLD FLASH
UNDERPLATING:50~120u" NICKEL OVERALL
- 3.SOLDER TAB:PHOSPHOR BRONZE
TOTAL:80~150u" TIN PLATED OVERALL
UNDERPLATING:50~120u" NICKEL OVERALL

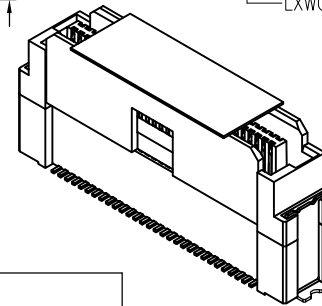
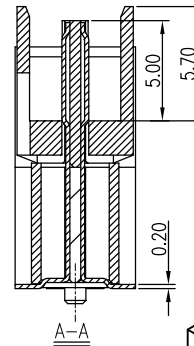
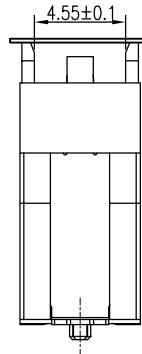
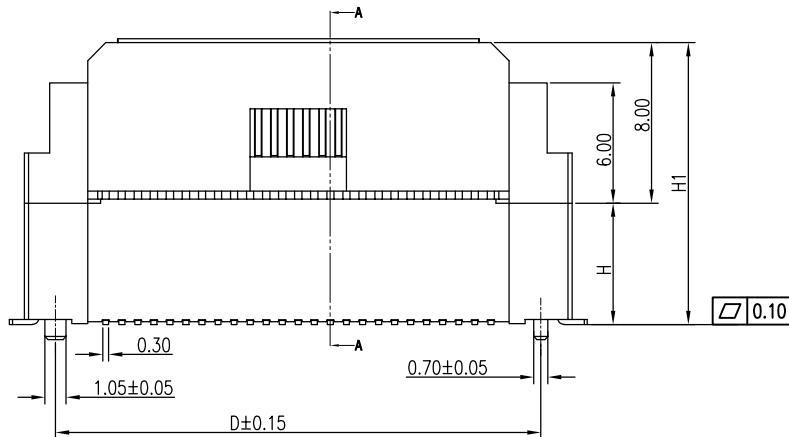
ELECTRICAL:

- 1.CURRENT RATING:0.5A 50V AC/DC
- 2.WITHSTANDING VOLTAGE:250V AC for 1 min
- 3.CONTACT RESISTANCE:65mΩ MAX
- 4.INSULATION RESISTANCE:100MΩ MIN

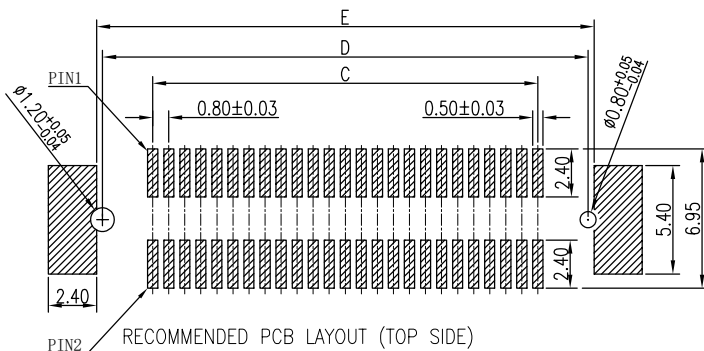
ENVIRONMENTAL:

1. OPERATING TEMPERATURE:-55°C TO +125°C.

LB18XX-G XX P-BOR
PACKING: R: CARRIER REEL
O:STANDARD SPECIFICATIONS
COLOR:BLACK/WHITE
P: PLUG
30~160PIN
PLATING TYPE G:1u" Au Min(GOLD FLASH)
HEIGHT:DIM H1(TABLE SEE)
8:0.8 PITCH
1:RUNNING NUMBER
LXWCONN BTB CONNECTOR SERIES



MATED HEIGHT					
PLUG	SOCLET H1				
	7.40	10.40	11.40	12.40	13.40
8.00	10.00	13.00	14.00	15.00	16.00
11.00	13.00	16.00	17.00	18.00	19.00
12.00	14.00	17.00	18.00	19.00	20.00
13.00	15.00	18.00	19.00	20.00	21.00
14.00	16.00	19.00	20.00	21.00	22.00



RECOMMENDED PCB LAYOUT (TOP SIDE)

TOLERANCES UNLESS OTHERWISE
SPEC. ±0.05

No.of Pins	Dimension				
	A	B	C	D	E
20	15.30	8.60	7.20	12.2	12.80
30	19.30	12.60	12.20	16.20	16.80
40	23.30	16.60	15.20	20.20	20.80
DIM H1	H	H1	50	27.30	20.60
80	---	8.00	60	31.30	24.60
A0	3.00	11.00	80	39.30	32.60
B0	4.00	12.00	100	47.30	40.60
C0	5.00	13.00	120	55.30	48.60
D0	6.00	14.00	160	71.30	64.60

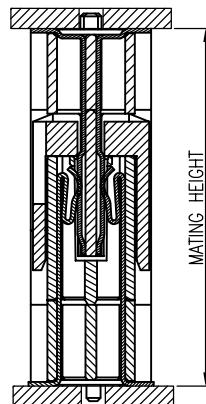
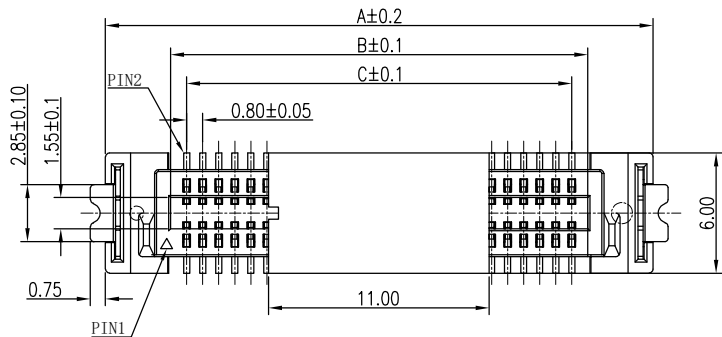
LXW 连兴旺电子(深圳)有限公司
connectivity LXWCONN ELECTRONICS(SHENZHEN) CO., LTD

品名(TITLE): 0.8mm B TO B D型公座
制图(DR): 2022.01.12
料号(PART NO): LB18XX-GXXP-BOR
比例(SCALE): 1:1
单位(UNITS): mm
张数(SHEET): 1 OF 1
图幅(SIZE): A4



版本 A (REV)	签名	日期
A0	NEW EDITION	East_Zhou 2022.01.12
修订 SER	修改摘要 REVISION DESCRIPTION	日期 DATE

一般公差
GENERAL TOLERANCE
X X X
±0.30
±0.50
±1.0
ANGLES
±2°



NOTES:

MATERIAL:

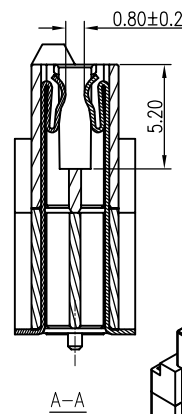
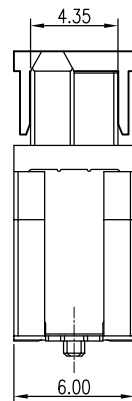
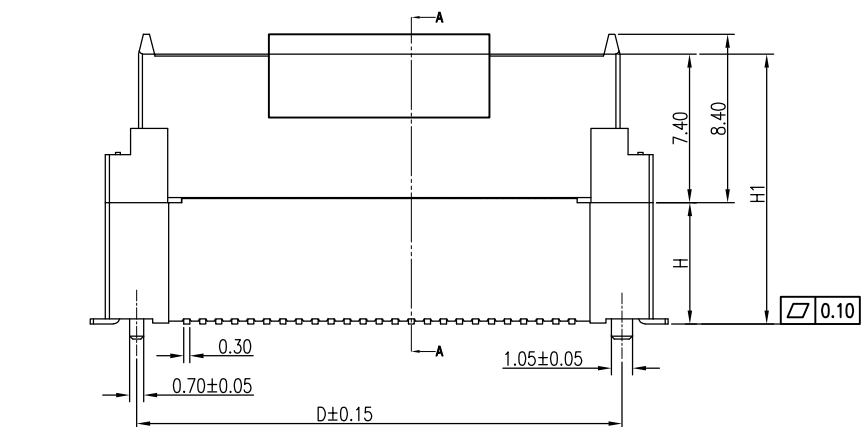
- 1.HOUSING:THERMO-PLASTIC. UL 94V-0 NATURE
- 2.CONTACT:PHOSPHOR BRONZE
CONTACT:SEE ORDER INF ORMATION; SOLDER:GOLD FLASH
UNDERPLATING:50~120u" NICKEL OVERALL
- 3.SOLDER TAB:PHOSPHOR BRONZE
TOTAL:80~150u" TIN PLATED OVERAL
UNDERPLATING:50~120u" NICKEL OVERALL

ELECTRICAL:

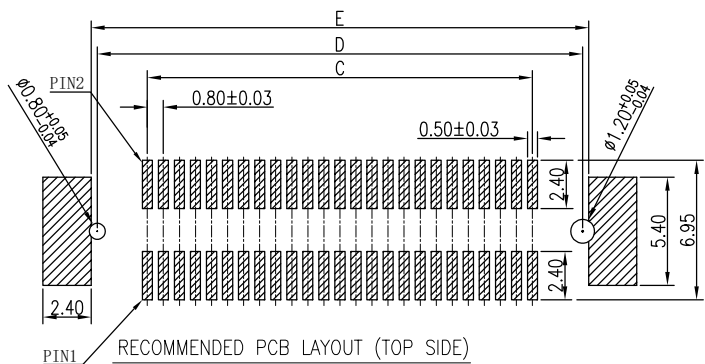
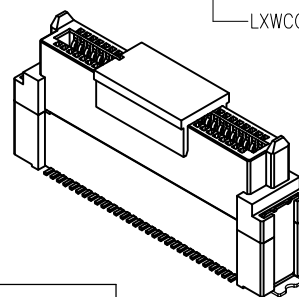
- 1.CURRENT RATING:0.5A 50V AC/DC
- 2.WITHSTANDING VOLTAGE:250V AC for 1 min
- 3.CONTACT RESISTANCE:65mΩ MAX
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ENVIRONMENTAL:

1. OPERATING TEMPERATURE:-55°C TO +125°C.



LB18XX-G XX S-BOR
PACKING: R: CARRIER REEL
O:STANDARD SPECIFICATIONS
COLOR:BLACK/WHITE
S: SOCKET
30~160PIN
PLATING TYPE G:1u" Au Min(GOLD FLASH)
HEIGHT:DIM H1(TABLE SEE)
8:0.8 PITCH
1:RUNNING NUMBER
LXWCONN BTB CONNECTOR SERIES



RECOMMENDED PCB LAYOUT (TOP SIDE)

TOLERANCES UNLESS OTHERWISE
SPEC. ±0.05

PLUG	MATED HEIGHT				
	SOCLET H1				
	7.40	10.40	11.40	12.40	13.40
8.00	10.00	13.00	14.00	15.00	16.00
11.00	13.00	16.00	17.00	18.00	19.00
12.00	14.00	17.00	18.00	19.00	20.00
13.00	15.00	18.00	19.00	20.00	21.00
14.00	16.00	19.00	20.00	21.00	22.00

No.of Pins	Dimension				
	A	B	C	D	E
20	15.30	8.80	7.20	12.2	12.80
30	19.30	12.80	12.20	16.20	16.80
40	23.30	16.80	15.20	20.20	20.80
DIM H1	H	H1	50	27.30	20.80
74	---	7.40	60	31.30	24.80
A4	3.00	10.40	80	39.30	32.80
B4	4.00	11.40	100	47.30	40.60
C4	5.00	12.40	120	55.30	48.80
D4	6.00	13.40	160	71.30	64.80



连兴旺电子(深圳)有限公司
LXWCONN ELECTRONICS(SHENZHEN) CO., LTD

一般公差
GENERAL TOLERANCE
X.XX ±0.30
X.XX ±0.10
ANGLES ±2°

EAST_ZHOU
制图(DR): 2022.01.12
品名(TITLE): 0.8mm BTOB D型母座
审核(CHEK):
料号(PART NO): LB18XX-GXXS-BOR
比例(SCALE) 1:1
单位(UNITS) mm
张数(SHEET) 1 OF 1
图幅(SIZE) A4



A0	NEW EDITION	East_Zhou	2022.01.12
修订 SER	修改摘要 REVISION DESCRIPTION	签名 SIGNATURE	日期 DATE